



## **“ESiP” Creates Reliable System-in-Package Demonstrators and Receives the 2013 ENIAC JU Innovation Award**

**Barcelona:** The ENIAC Joint Undertaking announced that the project “Efficient silicon multi-chip System-in-Package integration – reliability, failure analysis and test (ESiP)” received the 2013 Innovation Award for demonstrating high quality and reliability for applications from consumer to aeronautics.

40 partners from 9 countries engaged total costs of 36.1 million euro to raise to the challenges posed by heterogeneous integration, developing technologies, analytical methods and characterisation techniques to create high value components integrating a variety of functions protected by anti-counterfeiting features.

**Klaus Pressel**, the project leader of Infineon Technologies, said: “Large companies and SMEs built in the ESiP project over 20 test vehicle, acquiring in-depth knowledge on the specific failure mechanisms, developing the appropriate analytical techniques and building highly reliable innovative solutions capable to satisfy the most demanding requirements.”

The project resulted in more than 130 technical publications.

**Andreas Wild**, the Executive Director of the ENIAC Joint Undertaking, said: “The ENIAC JU Innovation Award recognizes each year the projects having contributed most to building an innovation-based future of growth and jobs in Europe. ESiP, the winner of this year, created world-class system integration technologies effectively meeting societal challenges.”

**ESiP Participants:** 3D-PLUS; ADVANCED LASER SEPARATION INTERNATIONAL NV; AMS AG; AUSTRIAN INSTITUTE OF TECHNOLOGY GMBH; BOSCHMAN TECHNOLOGIES B.V.; CASCADE MICROTECH DRESDEN GmbH; CEA-LETI; COMPART AS; DELFT UNIVERSITY OF TECHNOLOGY; EADS; EV GROUP E. THALLNER GMBH; FEINMETALL GMBH; FRAUNHOFER-GESELLSCHAFT ZUR FÖRDERUNG DER ANGEWANDTEN FORSCHUNG E.V.; INFINEON TECHNOLOGIES AG; INFRATEC GMBH; IMEC V.Z.W.; MELEXIS N.V.; MEMSSTAR LIMITED; MURATA ELECTRONICS OY; NETHERLANDS ORGANIZATION FOR APPLIED SCIENTIFIC RESEARCH; NXP SEMICONDUCTORS; OKMETIC OYJ; PHILIPS LIGHTING B.V.; PICOSUN OY; PVA TEPLA ANALYTICAL SYSTEMS; QUANTEMOL LTD.; SENSOROR AS; SIEMENS AG; SPEA S.P.A.; STIFTELSEN SINTEF; STMICROELECTRONICS (ROUSSET) SAS; STMICROELECTRONICS (TOURS) SAS; STMICROELECTRONICS S.r.l.; TEAM NANOTEC GMBH; TECHNOPROBE; TRONICO-ALCEN; UNIVERSITY COLLEGE LONDON; UNIVERSITY OF BOLOGNA; VTT TECHNICAL RESEARCH CENTRE OF FINLAND; ZENTRUM FÜR ELEKTRONENMIKROSKOPIE GRAZ

**ENIAC member States participating:** Austria; Belgium; Finland; France; Germany; Italy; Norway; The Netherlands; United Kingdom

**About the ENIAC Joint Undertaking:** The ENIAC Joint Undertaking (JU) is a public-private partnership on nanoelectronics bringing together the ENIAC member States, the European Union, and AENEAS (an association representing European R&D actors in this field). The total value of the R&D activities generated through this partnership is estimated at 3 B€.

Further information at [www.eniac.eu](http://www.eniac.eu)

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